INTEGRATED CIRCUITS

DATA SHEET

74F112Dual J-K negative edge-triggered flip-flop

Product specification

1990 Feb 09

IC15 Data Handbook





Philips Semiconductors Product specification

Dual J-K negative edge-triggered flip-flop

74F112

FEATURE

• Industrial temperature range available (-40°C to +85°C)

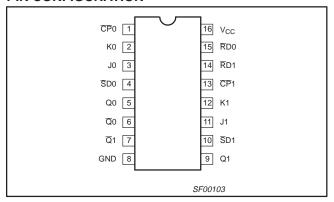
DESCRIPTION

The 74F112, Dual Negative Edge-Triggered JK-Type Flip-Flop, feature individual J, K, Clock $(\overline{\mathbb{CP}}n)$, Set $(\overline{\mathbb{SD}})$ and Reset $(\overline{\mathbb{RD}})$ inputs, true $(\mathbb{Q}n)$ and complementary $(\overline{\mathbb{Q}}n)$ outputs.

The \overline{SD} and \overline{RD} inputs, when Low, set or reset the outputs as shown in the Function Table, regardless of the level at the other inputs.

A High level on the clock ($\overline{CP}n$) input enables the J and K inputs and data will be accepted. The logic levels at the J and K inputs may be allowed to change while the $\overline{CP}n$ is High and flip-flop will perform according to the Function Table as long as minimum setup and hold times are observed. Output changes are initiated by the High-to-Low transition of the $\overline{CP}n$.

PIN CONFIGURATION



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F112	100MHz	15mA

ORDERING INFORMATION

	C		
DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$, $T_{amb} = 0^{\circ}C$ to +70°C	INDUSTRIAL RANGE V_{CC} = 5V $\pm 10\%$, T_{amb} = -40°C to +85°C	PKG DWG #
16-pin plastic DIP	N74F112N	I74F112N	SOT38-4
16-pin plastic SO	N74F112D	174F112D	SOT109-1

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

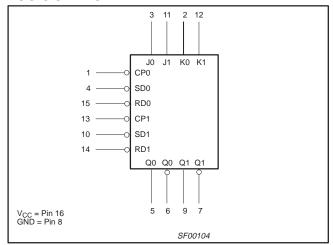
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
J0, J1	J inputs	1.0/1.0	20μA/0.6mA
K0, K1	K inputs	1.0/1.0	20μA/0.6mA
SD0, SD1	Set inputs (active Low)	1.0/5.0	20μA/3.0mA
RD0, RD1	Reset inputs (active Low)	1.0/5.0	20μA/3.0mA
CP0, CP1	Clock Pulse input (active falling edge)	1.0/4.0	20μA/2.4mA
Q0, Q0; Q1, Q1	Data outputs	50/33	1.0mA/20mA

NOTE:

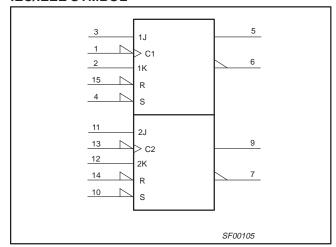
One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

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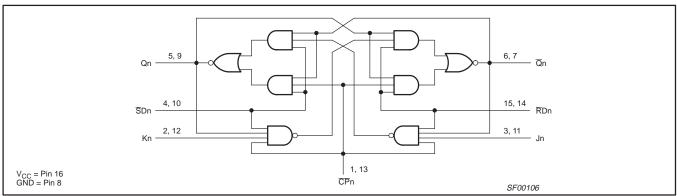
LOGIC SYMBOL



IEC/IEEE SYMBOL



LOGIC DIAGRAM



FUNCTION TABLE

		INPUTS			OUTPUTS		OPERATING MODE
SD	RD	CP	J	К	Q	Q	OFERATING MODE
L	Н	Х	Х	Х	Н	L	Asynchronous Set
Н	L	Х	Х	Х	L	Н	Asynchronous Reset
L	L	Х	Х	Х	H*	H*	Undetermined *
Н	Н	\downarrow	h	h	q	q	Toggle
Н	Н	\downarrow	1	h	L	Н	Load "0" (Reset)
Н	Н	\downarrow	h	I	Н	L	Load "1" (Set)
Н	Н	\downarrow	I	ı	q	q	Hold "no change"
Н	Н	Н	Х	Х	Q	Q	Hold "no change"

H = High voltage level

h = High voltage level one setup time prior to High-to-Low clock transition

L = Low voltage level

I = Low voltage level one setup time prior to High-to-Low clock transition

q = Lower case letters indicate the state of the reference output prior to the High-to-Low clock transition

X = Don't care

 \downarrow = High-to-Low clock transition

* = Both outputs will be High while both SD and RD are Low, but the output states are unpredictable if SD and RD go High simultaneously.

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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT	
V _{CC}	Supply voltage		-0.5 to +7.0	V	
V _{IN}	Input voltage	-0.5 to +7.0	V		
I _{IN}	Input current	−30 to +5	mA		
V _{OUT}	Voltage applied to output in High output state	Voltage applied to output in High output state			
I _{OUT}	Current applied to output in Low output state		40	mA	
_		Commercial range	0 to +70	°C	
^I amb	Operating free-air temperature range	Industrial range	-40 to +85	°C	
T _{stg}	Storage temperature range	-	-65 to +150	°C	

RECOMMENDED OPERATING CONDITIONS

CVMDOL	DADAMETED			LIMITS		LINUT
SYMBOL	PARAMETER	MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage	4.5	5.0	5.5	V	
V _{IH}	High-level input voltage		2.0			V
V _{IL}	Low-level input voltage				0.8	V
I _{IK}	Input clamp current				-18	mA
I _{OH}	High-level output current				-1	mA
I _{OL}	Low-level output current				20	mA
_		Commercial range	0		+70	°C
T _{amb}	Operating free-air temperature range	Industrial range	-40		+85	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

CVMDOL	DADAMETED		TEST CONDITION	NC1		LIMITS		UNIT
SYMBOL	PARAMETER		TEST CONDITIO	MIN	TYP ²	MAX	Olviii	
V	High lovel output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}	2.5			V
V _{OH}	High-level output voltage		$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V
V	Low lovel output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}		0.35	0.50	V
V _{OL}	Low-level output voltage		V _{IH} = MIN, I _{OL} = MAX	±5%V _{CC}		0.35	0.50	V
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$			-0.73	-1.2	V
I _I	Input current at maximum input v	oltage	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
		Jn, Kn					-0.6	mA
I _{IL}	Low-level input current	CPn	$V_{CC} = MAX, V_I = 0.5V$				-2.4	mA
		SDn, RDn					-3.0	mA
Ios	Short-circuit output current ³		V _{CC} = MAX		-60		-150	mA
I _{CC}	Supply current (total) ⁴		V _{CC} = MAX	·		15	21	mA

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
 Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
- 4. Measure I_{CC} with the clock input grounded and all outputs open, with the Q and \overline{Q} outputs High in turn.

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AC ELECTRICAL CHARACTERISTICS

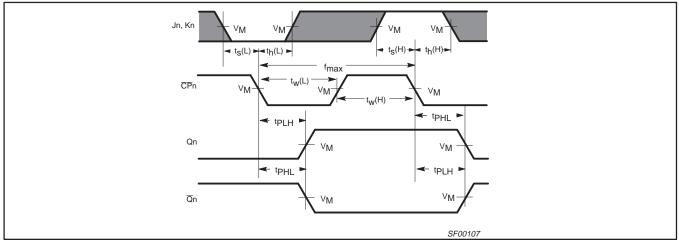
						LI	MITS			
SYMBOL	PARAMETER	TEST CONDITION	$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_{L} = 50pF$ $R_{L} = 500\Omega$			$V_{CC} = +5.0V \pm 10\% \\ T_{amb} = 0^{\circ}C \text{ to } +70^{\circ}C \\ C_{L} = 50pF \\ R_{L} = 500\Omega$		$V_{CC} = +5.0V \pm 10\%$ $T_{amb} = -40^{\circ}C \text{ to } +85^{\circ}C$ $C_{L} = 50pF$ $R_{L} = 500\Omega$		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{MAX}	Maximum clock frequency	Waveform 1	85	100		80		80		MHz
t _{PLH} t _{PHL}	Propagation delay CP to Qn or Qn	Waveform 1	2.0 2.0	5.0 5.0	6.5 6.5	2.0 2.0	7.5 7.5	2.0 2.0	7.5 7.5	ns
t _{PLH}	Propagation delay SDn, RD to Qn or Qn	Waveform 2,3	2.0 2.0	4.5 4.5	6.5 6.5	2.0 2.0	7.5 7.5	1.5 1.5	7.5 7.5	ns

AC SETUP REQUIREMENTS

						LI	MITS			
SYMBOL	PARAMETER	TEST CONDITION	$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_{L} = 50pF$ $R_{L} = 500\Omega$			$V_{CC} = +5.0V \pm 10\%$ $T_{amb} = 0^{\circ}C \text{ to } +70^{\circ}C$ $C_{L} = 50pF$ $R_{L} = 500\Omega$		$V_{CC} = +5.0V \pm 10\%$ $T_{amb} = -40^{\circ}C \text{ to } +85^{\circ}C$ $C_{L} = 50pF$ $R_{L} = 500\Omega$		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _S (H) t _S ((L)	Setup time, High or Low Jn, Kn to CP	Waveform 1	4.0 3.5			5.0 4.0		5.0 4.0		ns
t _h (H) t _h (L)	Hold time, High or Low Jn, Kn to CP	Waveform 1	0.0 0.0			0.0 0.0		0.0 0.0		ns
t _W (H) t _W (L)	CP Pulse width High or Low	Waveform 1	4.5 4.5			5.0 5.0		5.0 5.0		ns
t _W (L)	SDn, RD Pulse width Low	Waveform 2,3	4.5			5.0	·	5.0		ns
t _{REC}	Recovery time SDn, RD to CP	Waveform 2,3	4.5			5.0		5.0		ns

AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.



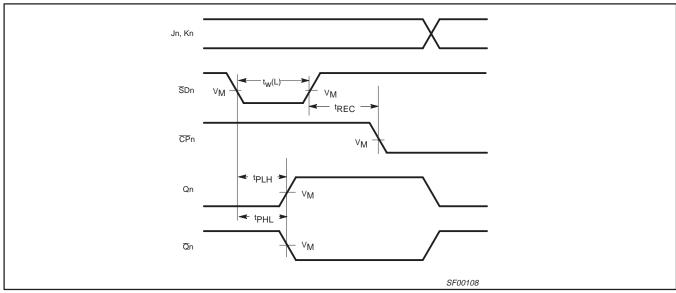
The shaded areas indicate when the input is permitted to change for predictable output performance.

Waveform 1. Propagation Delay for Data to Output, Data Setup Time and Hold Times, and Clock Pulse Width

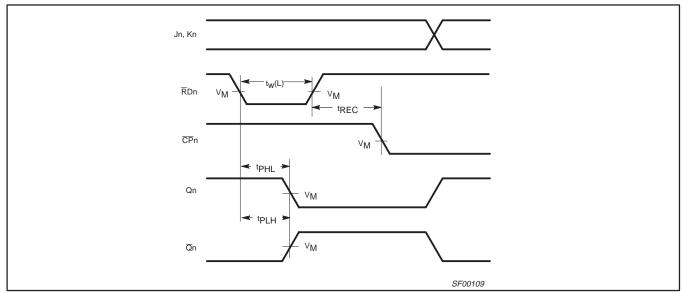
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Waveform 2. Propagation Delay for Set to Output, Set Pulse Width, and Recovery Time for Set to Clock

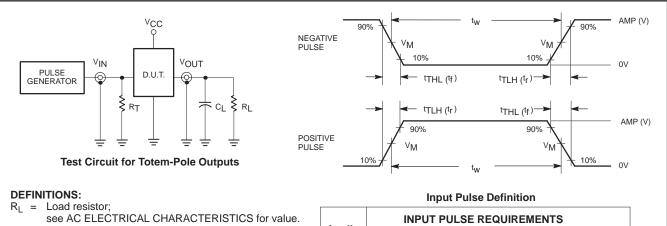


Waveform 3. Propagation Delay for Reset to Output, Reset Pulse Width, and Recovery Time for Reset to Clock

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TEST CIRCUIT AND WAVEFORMS



 $C_L = Load$ capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

Termination resistance should be equal to Z_{OUT} of pulse generators.

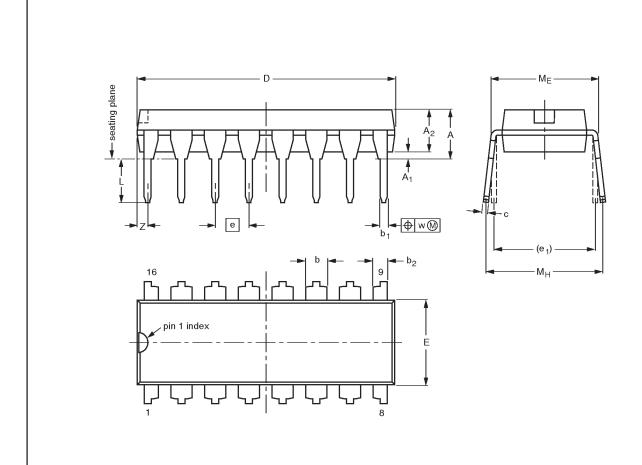
family	INPUT PULSE REQUIREMENTS									
family	amplitude	V _M rep. rate		t _w	t _{TLH}	t _{THL}				
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns				

SF00006

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DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UN	VIT.	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	C	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
m	m	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
incl	hes	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

10 mm

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

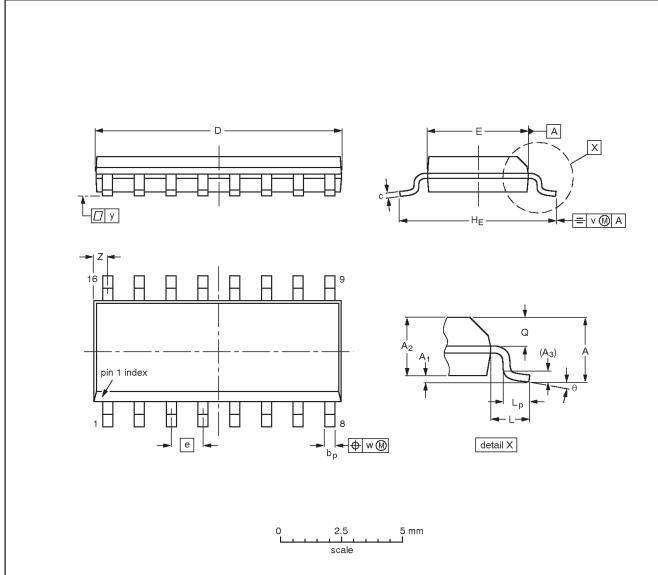
OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	EIAJ		ISSUE DATE
SOT38-4						-92-11-17 95-01-14

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SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT109-1	076E07S	MS-012AC				95-01-23 97-05-22

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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